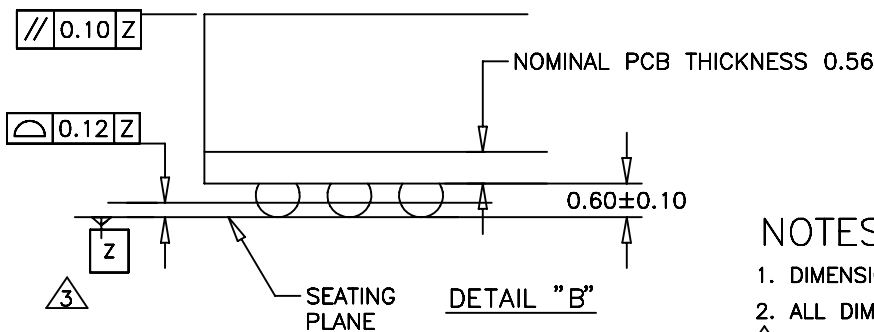
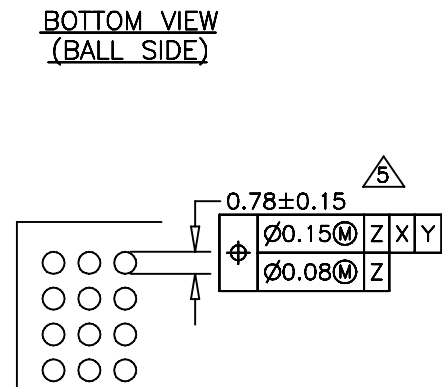
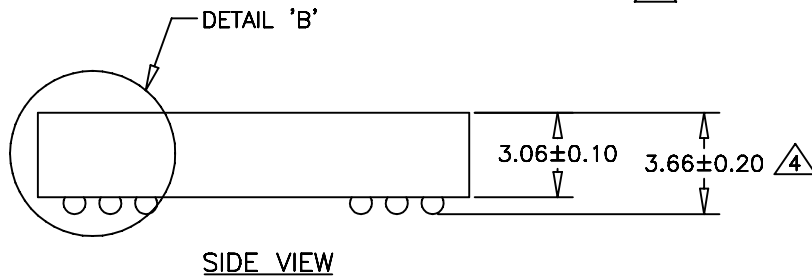
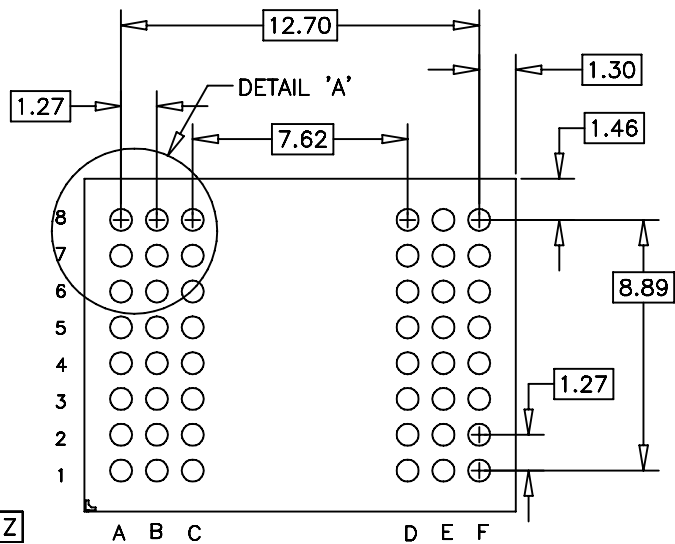
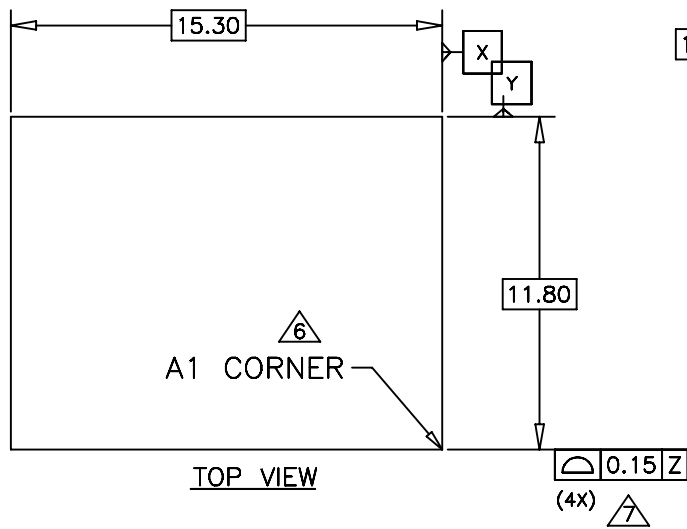


REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	05/04	



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. PRIMARY DATUM -Z- AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. THIS DIMENSION INCLUDES STAND-OFF HEIGHT AND PACKAGE BODY THICKNESS
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM -Z-.
6. A1 CORNER MUST BE IDENTIFIED BY INK/LASER MARK ON TOP PACKAGE, AND METALLIZED MARKINGS ON BOTTOM PACKAGE
7. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
8. BASIC SOLDER BALL PITCH IS 1.27 MM

SIGNATURE	DATE
DOC. CONTROL:	
ENGR. MGR:	
MFG. ENGR:	
CHECKED BY:	TWM 05/04
DRAWN BY:	JD 05/04

**DALLAS SEMICONDUCTOR**

MARKETING OUTLINE, 48L WIRE BOND BGA, 15.30 X 11.80MM, 1.27 MM PITCH, 3.66 MM THICK

SIZE	FSCM NO.	PART NO.	REV.
A		56-G6030-001	A
SCALE	N/A		SHEET 1 of 1